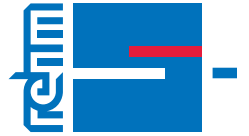
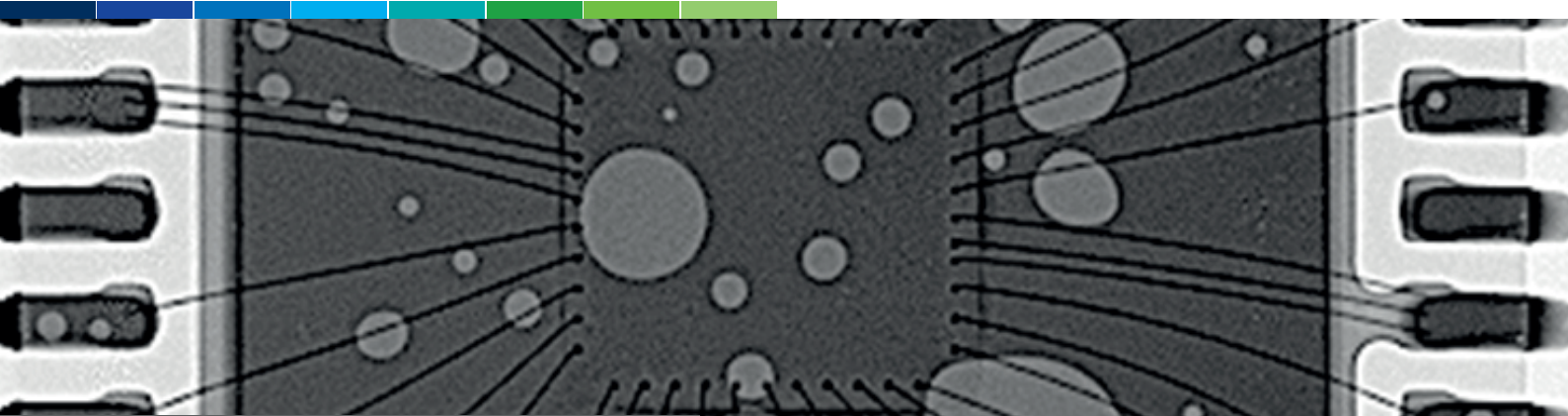


WEBINAR

Reduction of Void Formation with Vacuum



THERMAL SYSTEMS



September 29, 2021 at 9:00 a.m. and 4:00 p.m.

Vacuum soldering has been a proven technique for decades in contact heat and vapour phase soldering systems, significantly reducing gas bubbles in solder joints. What does this mean in terms of convection soldering, though, the most widely used and highest-throughput soldering technique today?

In our webinar we explain the possibilities of different vacuum soldering processes and also show the corresponding limits.

September 29, 2021 9.00 a.m. CEST (for Asia, Europe, ROW)
4:00 p.m. CEST (for Americas, Europe)

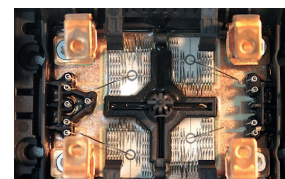
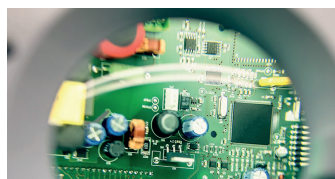
Registration:
sales@rehm-group.com

Duration of the webinar: 60 min

Main topics of the webinar

- Basics of void formation
- Acceptance criteria of void contents – Guidelines and Standards
- Effect of vacuum on void formation
- Comparison of soldering systems with vacuum: Convection, Condensation and Contact heat
- Q&A

Subject to substantive adjustments



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